

# FDD8782/FDU8782

# N-Channel PowerTrench® MOSFET

**25V, 35A, 11m**Ω

# Features



#### **General Description**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $r_{DS(on)}$  and fast switching speed.

### Application

- Vcore DC-DC for Desktop Computers and Servers
- VRM for Intermediate Bus Architecture

- Max  $r_{DS(on)} = 11.0 m\Omega$  at  $V_{GS} = 10 V$ ,  $I_D = 35 A$
- Max  $r_{DS(on)}$  = 14.0m $\Omega$  at  $V_{GS}$  = 4.5V,  $I_D$  = 35A
- Low gate charge:  $Q_{g(10)} = 18nC(Typ)$ ,  $V_{GS} = 10V$
- Low gate resistance
- Avalanche rated and 100% tested
- RoHS Compliant



#### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
$V_{DS}$	Drain to Source Voltage		25	V
$V_{GS}$	Gate to Source Voltage		±20	V
	Drain Current -Continuous (Package Limited)		35	
I <sub>D</sub>	-Continuous (Die Limited)		54	Α
	-Pulsed	(Note 1)	321	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 2)	70	mJ
$P_{D}$	Power Dissipation		50	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to 175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case TO-252,TO-251	3.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252,TO-251	100	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252,1in <sup>2</sup> copper pad area	52	°C/W

### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD8782	FDD8782	TO-252AA	13"	12mm	2500 units
FDU8782	FDU8782	TO-251AA	N/A(Tube)	N/A	75 units
FDU8782	FDU8782_F071	TO-251AA	N/A(Tube)	N/A	75 units

Electrical Cha	aracteristics	T <sub>J</sub> = 25°C unless ot	herwise noted
----------------	---------------	---------------------------------	---------------

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	25			V
$\frac{\Delta B_{VDSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25°C		14.3		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1 250	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = ±20V			±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.2	1.7	2.5	V	
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25°C		-6.5		mV/°C	
	Drain to Source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 35A		8.5	11.0		
rpovers		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 35A		11.0	14.0	mΩ	
r <sub>DS(on)</sub>	Drain to course on registance	$V_{GS}$ = 10V, $I_D$ = 35A $T_J$ = 175°C		12.1	18.0	mΩ	

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V - 42V V - 0V	920	1220	pF
Coss	Output Capacitance	V <sub>DS</sub> = 13V, V <sub>GS</sub> = 0V, — f = 1MHz	230	310	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 111112	160	240	pF
$R_g$	Gate Resistance	f = 1MHz	1.4		Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		7	14	ns
t <sub>r</sub>	Rise Time	$V_{DD}$ = 13V, $I_{D}$ = 35A $V_{GS}$ = 10V, $R_{GS}$ = 9 $\Omega$	9	18	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10V, R <sub>GS</sub> = 912	22	36	ns
t <sub>f</sub>	Fall Time		14	25	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0V to 10V	18	25	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } 5V$ $V_{DD} = 13V$ $I_{D} = 35A$	9.4	13	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	$I_D = 35A$ $I_D = 1.0 \text{mA}$	3.1		nC
$Q_{gd}$	Gate to Drain "Miller" Charge	.g	4.0		nC

#### **Drain-Source Diode Characteristics**

	Source to Drain Diode, Ferward Voltage	$V_{GS} = 0V, I_{S} = 35A$	0.96	1.25	\/	
	V <sub>GS</sub> = 0V, I <sub>S</sub> = 15A	0.86	1.2	V		
t <sub>r</sub>	т	Reverse Recovery Time	$I_F = 35A$ , di/dt = 100A/ $\mu$ s	25	38	ns
C	Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = 35A$ , di/dt = 100A/ $\mu$ s	17	26	nC

Notes:
1: Pulse time < 300us, Duty cycle = 2%.
2: Starting T<sub>J</sub> = 25°C, L = 0.3mH, I<sub>AS</sub> = 21.7A ,V<sub>DD</sub> = 23V, V<sub>GS</sub> = 10V.



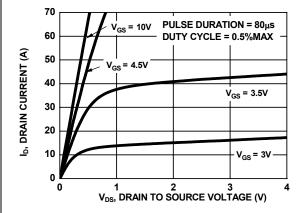


Figure 1. On Region Characteristics

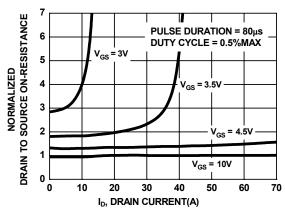


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

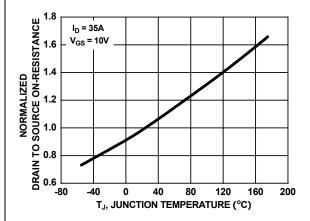


Figure 3. Normalized On Resistance vs Junction Temperature

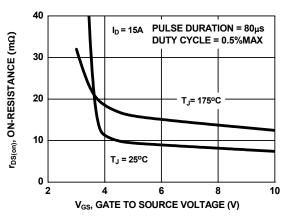


Figure 4. On-Resistance vs Gate to Source Voltage

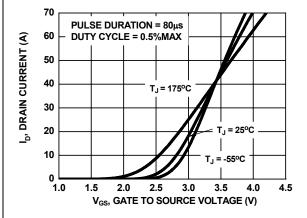


Figure 5. Transfer Characteristics

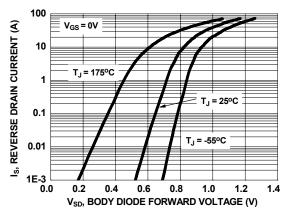
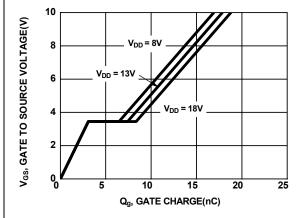


Figure 6. Source to Drain Diode Forward Voltage vs Source Current





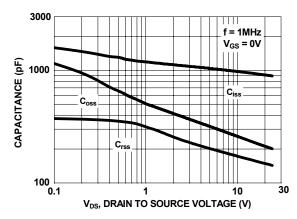
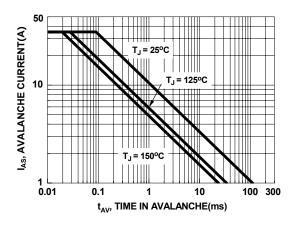


Figure 7. Gate Charge Characteristics

Figure 8. Capacitance vs Drain to Source Voltage



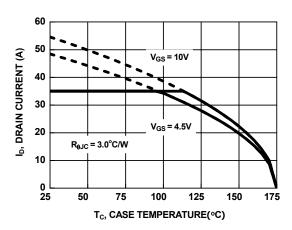
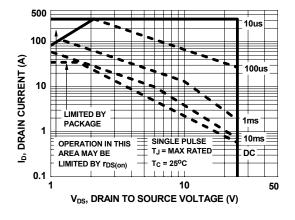


Figure 9. Unclamped Inductive Switching Capability

Figure 10. Maximum Continuous Drain Current vs Case Temperature



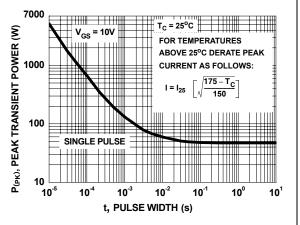


Figure 11. Forward Bias Safe Operating Area

Figure 12. Single Pulse Maximum Power Dissipation



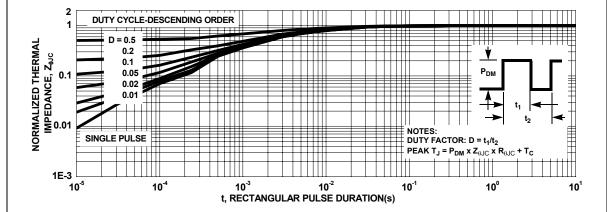


Figure 13. Transient Thermal Response Curve

#### **TRADEMARKS**

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FAST®	ISOPLANAR™	PowerEdge™	SuperFET™
ActiveArray™	FASTr™	LittleFET™	PowerSaver™	SuperSOT™-3
Bottomless™	FPS™	MICROCOUPLER™	PowerTrench®	SuperSOT™-6
Build it Now™	FRFET™	MicroFET™	QFET <sup>®</sup>	SuperSOT™-8
CoolFET™	GlobalOptoisolator™	MicroPak™	QS™	SyncFET™
CROSSVOLT™	GTO™	MICROWIRE™	QT Optoelectronics™	TCM™
DOME™	HiSeC™	MSX™	Quiet Series™	TinyLogic <sup>®</sup>
EcoSPARK™	I <sup>2</sup> C™	MSXPro™	RapidConfigure™	TINYOPTO™
E <sup>2</sup> CMOS™	i-Lo™	OCX <sup>TM</sup>	RapidConnect™	TruTranslation™
EnSigna™	ImpliedDisconnect™	OCXPro™	μSerDes™	UHC™
FACT™	IntelliMAX™	OPTOLOGIC <sup>®</sup>	ScalarPump™	UniFET™
FACT Quiet Series	TM	OPTOPLANAR™	SILENT SWITCHER®	UltraFET <sup>®</sup>
Across the board. A	Around the world.™	PACMAN™	SMART START™	VCX <sup>TM</sup>
The Power Franchise®		POP <sup>TM</sup>	SPM™	Wire™
Programmable Active Droop™		Power247™	Stealth™	

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

#### As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## PRODUCT STATUS DEFINITIONS Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.